

Epoxy Technology EPO-TEK® E3035T-2 Electrically Conductive Epoxy

Category : Polymer , Thermoset , Epoxy , Epoxy, Electrically Conductive

Material Notes:

Product Description: EPO-TEK® E3035T-2 is a single component, silver-filled epoxy for semiconductor die attach, as well as SMD attach on hybrid circuits. **Advantages & Application Notes:** This epoxy can be classified as a higher viscosity version of EPO-TEK® E3035, suggested for the following purposes: Used for improved stencil printing via small apertures. Less flow-out between small pads like 0402 or 0603 caps and resistors. Performs exceptionally well as a die attach for small chips such as GaAs, LEDs and diodes. Capable of resisting 260°C green reflow process, low outgassing in hermetic lid-seal processes near 300°C, and organic burn-in up to 150°C/1000 hours storage. Low levels of water extractable monovalent ions such as Chlorides. Capable of JEDEC Level II die-attach packaging on die-paddles and lead-frames. Widely used epoxy; popular choice for silver-filled epoxies; opto-packaging, hybrids, and many types of substrates including kovar, ceramic and BT Contact techserv@epotek.com for your best recommendation. Alternate viscosities and lower curing temperatures are available. Information Provided by Epoxy Technology

Order this product through the following link:

http://www.lookpolymers.com/polymer_Epoxy-Technology-EPO-TEK-E3035T-2-Electrically-Conductive-Epoxy.php

Physical Properties	Metric	English	Comments
Specific Gravity	1.13 g/cc	1.13 g/cc	
Particle Size	<= 20 µm	<= 20 µm	
Viscosity	80000 - 120000 cP @Temperature 23.0 °C	80000 - 120000 cP @Temperature 73.4 °F	2.5 rpm

Mechanical Properties	Metric	English	Comments
Hardness, Shore D	85	85	
Tensile Modulus	2.55 GPa	369 ksi	Storage
Shear Strength	12.25 MPa	1776 psi	Lap
	>= 23.4 MPa	>= 3400 psi	Die

Thermal Properties	Metric	English	Comments
CTE, linear	42.0 µm/m-°C	23.3 µin/in-°F	Below Tg
	80.0 µm/m-°C	44.4 µin/in-°F	Above Tg
Thermal Conductivity	1.44 W/m-K	9.99 BTU-in/hr-ft²-°F	
Maximum Service Temperature, Air	200 °C	392 °F	Continuous
	300 °C	572 °F	Intermittent

Minimum Service Temperature, Air Thermal Properties	-55.0 °C Metric	-67.0 °F English	Continuous Comments
	-55.0 °C	-67.0 °F	Intermittent
Glass Transition Temp, Tg	>= 100 °C	>= 212 °F	Dynamic Cure 20—200°C /ISO 25 Min; Ramp -10—200°C @ 20°C/Min
Decomposition Temperature	390 °C	734 °F	Degradation Temperature; TGA

Electrical Properties	Metric	English	Comments
Volume Resistivity	<= 0.00050 ohm-cm	<= 0.00050 ohm-cm	

Chemical Properties	Metric	English	Comments
Ionic Impurities - Na (Sodium)	21 ppm	21 ppm	
Ionic Impurities - K (Potassium)	3.0 ppm	3.0 ppm	
Ionic Impurities - Cl (Chloride)	62 ppm	62 ppm	

Processing Properties	Metric	English	Comments
Cure Time	60.0 min @Temperature 180 °C	1.00 hour @Temperature 356 °F	Minimum Bond Line
Pot Life	40320 min	40320 min	
Shelf Life	12.0 Month @Temperature -40.0 °C	12.0 Month @Temperature -40.0 °F	

Descriptive Properties	Value	Comments
Color	Silver	
Consistency	Thixotropic paste	
Ionic Impurities NH4	24 ppm	
Number of Components	Single	
Thixotropic Index	4.09	
Weight Loss	0.15%	200°C
	0.29%	250°C
	0.32%	300°C

Contact Songhan Plastic Technology Co.,Ltd.

Website : www.lookpolymers.com

Email : sales@lookpolymers.com

Tel : +86 021-51131842

Mobile : +86 13061808058

Skype : lookpolymers

Address : United North Road 215,Fengxian District, Shanghai City,China